

AMENDMENTS TO THE SPECIFICATION

IN THE SPECIFICATION:

Please amend the paragraph beginning on page 1, line 13, as follows:

Recently, various fine processing technologies are studied and investigated, for highly integration and enhanced abilities of LSI. Of them, chemical mechanical polishing (chemical mechanical polishing, hereinafter, may be abbreviated as CMP) is ~~noticed~~ noted. CMP is a technology combining a chemical action and a mechanical action between a polishing composition and a polishing subject, and is an essential technology particularly in flattening an interlayer insulation film in a multi-layer wiring formation process, forming a metal plug, and forming an embedded metal wiring. The embedded metal wiring is formed by forming a metal film on a substrate and polishing this film.

Please amend the paragraph beginning on page 2, line 1, as follows:

In conventional CMP of a metal film, it is general to conduct polishing while feeding a polishing slurry containing abrasive particles into between a polishing subject and a polishing pad.

However, in this method, the surface of a metal film is scratched and roughened, ~~abrasive~~ abrasives are embedded in a the metal film, and further, a slurry has to be discarded. Therefore, it is investigated to conduct CMP by a pad itself without using a polishing slurry. As the polishing pad used ~~of~~ in CMP, a complex called non-woven fabric type composed of polyester fiber and polyurethane resin, and a porous polyurethane, and the like are usually used.

Please amend the paragraph beginning on page 2, line 11, as follows:

For the purpose of improving polishing speed, simplifying waste liquid treatment, and the like, use of a urethane foamed body pad obtained by adding particles of an inorganic oxide such as silica, ceria, alumina and the like as an abrasive particle previously into a polishing pad is investigated, however, the polishing speed is not recognized as satisfactory, and the surface of a metal is scratched by ~~an~~ the inorganic oxide particle and roughened.

Please amend the paragraph beginning on page 3, line 3, as follows:

The present inventors have intensively studied ~~for solving~~ to solve the above-mentioned problems, and resultantly found that the object can be attained by using a metal polishing pad having a functional group which captures a metal ion, ~~and~~. Consequently, the inventors have completed the present invention.

Please amend the paragraph beginning on page 9, line 22, as follows:

Of these ion exchange resins and ion exchange fiber having a functional group capturing a metal ion, the chelate resin or chelate fiber is a resin or fiber having on the surface a polydentate ligand having a plurality of coordinating atoms forming a complex with a metal. In general, when a polydentate ligand having two or more coordinating atoms is bonded to a metal ion, a chelate ring is formed, and stability thereof increases higher than of a complex in which a unidentate ligand is coordinated, and consequently, ~~an~~ the ability of capturing a metal ion, and polishing the subject increases, desirably.

Before the paragraph beginning on page 20, line 2, please add the following heading:

Comparative Example 1